V_{CC} [] 22

2Q7 23

2Q8 224

GND 25

2Q9 26 20E 27

28

2CLR

35 V_{CC}

34 2D7

33 🛛 2D8

32 GND 31 2D9

30 2 2 CLKEN

29 20LK

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 Members of the Texas Instruments Widebus™ Family Inputs Are TTL-Voltage Compatible 	54ACT16823 WD PACKAGE 74ACT16823 DL PACKAGE (TOP VIEW)					
 Provide Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity 	1 <u>CLR</u> 1 <u>OE</u> 1 <u>Q1</u> 3	56] 1CLK 55] 1CLKEN 54] 1D1				
 Flow-Through Architecture Optimizes PCB	GND 4	53 GND				
Layout	1Q2 5	52 1D2				
 Distributed V_{CC} and GND Pin Configuration	1Q3 6	51] 1D3				
Minimizes High-Speed Switching Noise	V _{CC} 7	50] V _{CC}				
 EPIC[™] (Enhanced-Performance Implanted	1Q4 8	49 1D4				
CMOS) 1-µm Process	1Q5 9	48 1D5				
 Package Options Include Plastic 300-mil	1Q6 10	47 1D6				
Shrink Small-Outline (DL) Packages Using	GND 11	46 GND				
25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD)	1Q7 12 1Q8 13 1Q9 14	45 1D7 44 1D8 43 1D9				
Packages Using 25-mil Center-to-Center	2Q1 [15	42 2D1				
Pin Spacings	2Q2 [16	41 2D2				
description	2Q3 17 GND 18	40 2D3 39 GND				
These 18-bit flip-flops feature 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. They are	2Q4 [] 19 2Q5 [] 20 2Q6 [] 21	38 2D4 37 2D5 36 2D6				

or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, parity bus interfacing, and working registers.

The 'ACT16823 can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable (CLKEN) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking CLKEN high disables the clock buffer, thus latching the outputs. Taking the clear (CLR) input low causes the Q outputs to go low independently of the clock.

A buffered output-enable (OE) input can be used to place the outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. OE does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered

while the outputs are in the high-impedance state.

The 74ACT16823 is packaged in the TI shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16823 is characterized for operation over the full military temperature range of 55°C to 125°C. The 74ACT16823 is characterized for operation from -40°C to 85°C



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54ACT16823, 74ACT16823 18-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS SCAS160A – APRIL 1991 – REVISED APRIL 1996

FUNCTION TABLE (each 9-bit stage)

(**************************************												
		INPUTS			OUTPUT							
OE	CLR	CLKEN	CLK	D	Q							
L	L	Х	Х	Х	L							
L	Н	L	\uparrow	Н	н							
L	Н	L	\uparrow	L	L							
L	Н	L	L	Х	Q ₀							
L	Н	Н	Х	Х	Q ₀							
н	Х	Х	Х	Х	Z							

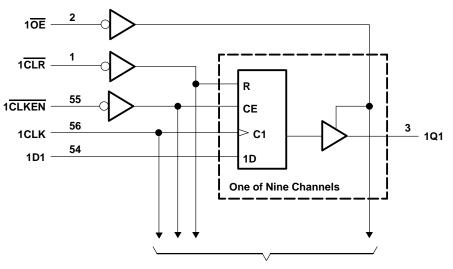
logic symbol[†]

			1	
1 <mark>0E</mark>	2	EN1		
1CLR	1	R2		
1CLKEN	55	G3		
1CLK	56	> 3C4		
20E	27	EN5		
20E 2CLR	28	R6		
2CLR 2CLKEN	30			
	29	G7		
2CLK		► 7C8		
1D1	54	4D 1, 2 ▽	3	1Q1
1D2	52		5	1Q2
1D3	51	-	6	1Q3
1D4	49		8	1Q4
1D4	48		9	1Q5
1D5	47		10	1Q6
1D0 1D7	45		12	1Q7
1D7 1D8	44		13	1Q7
1D8 1D9	43		14	
	42		15	1Q9
2D1	41	8D 5,6 ⊽	16	2Q1
2D2	40		17	2Q2
2D3	38	 	19	2Q3
2D4	37		20	2Q4
2D5	36		21	2Q5
2D6	34		23	2Q6
2D7	33	ļ	24	2Q7
2D8	31	ļ	25	2Q8
2D9				2Q9

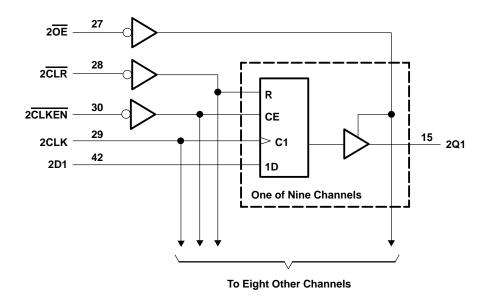
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To Eight Other Channels





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	
Output voltage range, V _O (see Note 1)(
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC})	±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±450 mA
Maximum package power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 2)

		54	ACT168	23	74	ACT1682	23	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2		h	2			V
VIL	Low-level input voltage		ľn,	0.8			0.8	V
VI	Input voltage	0	RE	VCC	0		VCC	V
Vo	Output voltage	0	1	VCC	0		VCC	V
ЮН	High-level output current		50	-24			-24	mA
IOL	Low-level output current	201	5	24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
Т _А	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



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	TEST CONDITIONS	N	T,	A = 25°0	;	54ACT	16823	74ACT	16823	
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	1	4.5 V	4.4			4.4		4.4		
	I _{OH} = -50 μA	5.5 V	5.4			5.4		5.4		
Vон	1	4.5 V	3.94			3.8		3.8		V
	I _{OH} = -24 mA	5.5 V	4.94			4.8		4.8		
	I _{OH} = –75 mA [†]	5.5 V				3.85		3.85		
	1	4.5 V			0.1		0.1		0.1	
	l _{OL} = 50 μA	5.5 V			0.1		0.1		0.1	
VOL	1 24	4.5 V			0.36		0.44		0.44	V
	$I_{OL} = 24 \text{ mA}$	5.5 V			0.36	4	0.44		0.44	
	I _{OL} = 75 mA [†]	5.5 V				c_{γ}	1.65		1.65	
Ц	$V_I = V_{CC}$ or GND	5.5 V			±0.1	201	±1		±1	μA
I _{OZ}	$V_{O} = V_{CC}$ or GND	5.5 V			±0.5	R	±5		±5	μA
ICC	$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	5.5 V			8		80		80	μA
ΔI_{CC}^{\ddagger}	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1		1	mA
Ci	V _I = V _{CC} or GND	5 V		3						pF
Co	$V_{O} = V_{CC}$ or GND	5 V		12						pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡]This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A =	25°C	54ACT	16823	74ACT	16823	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
^f clock	Clock frequency		0	90	0	90	0	90	MHz
t	Pulse duration	CLR low	3.3		3.3	15	3.3		
tw		CLK high or low	5.5		5.5	25	5.5		ns
		CLR inactive	0.5		0.5	Q.	0.5		
t _{su}	Setup time before CLK↑	Data	7		3		7		ns
		CLKEN low	3.5		3.5		3.5		
•.		Data			0.5		0.5		
th	Hold time after CLK↑	CLKEN high or low	2.5		2.5		2.5		ns



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

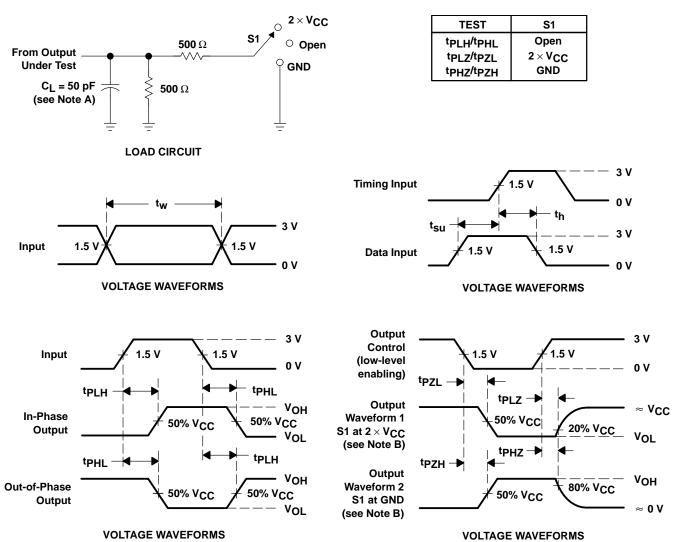
PARAMETER	FROM	то		₄ = 25°C	;	54ACT	16823	74ACT	16823	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
fmax			90			90	2	90		MHz
^t PLH	CLK	Q	4.2	7.5	10.6	4.2	12.1	4.2	12.1	ns
^t PHL	-	Q	4.8	8.3	11.5	4.8	12.9	4.8	12.9	115
^t PHL	CLR	Q	3.4	7.3	11.2	3.4	12.5	3.4	12.5	ns
^t PZH	OE	Q	2.4	5.9	9.5	2.4	10.7	2.4	10.7	20
^t PZL	UE	Q	3.3	7.1	11.3	3.3	12.8	3.3	12.8	ns
^t PHZ		Q	5.5	7.6	9.7	5.5	10.3	5.5	10.3	
^t PLZ	OE	y y	4.6	6.7	8.8	4.6	9.4	4.6	9.4	ns

operating characteristics, V_{CC} = 5 V, T_A = 25° C

	PARAMETER	TEST CO	TYP	UNIT	
C _{pd} Power dissipation capacitance per flip-flop	Outputs enabled	C ₁ = 50 pF. f = 1 MHz		42	рF
	Power dissipation capacitance per hip-hop	Outputs disabled	C _L = 50 pF,	f = 1 MHz	24



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 3 ns, t_f = 3 ns.

D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ACT16823DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16823DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16823DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16823DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



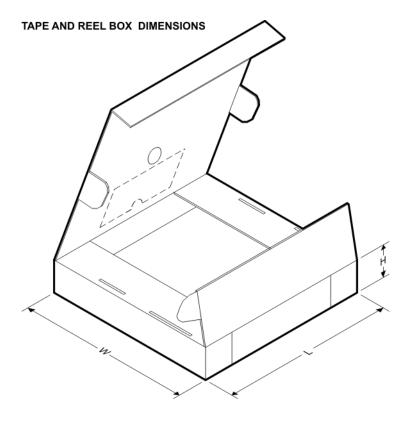
*All dimensions are nominal	
-----------------------------	--

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16823DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT16823DLR	SSOP	DL	56	1000	346.0	346.0	49.0

MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



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